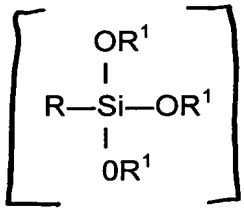
Amendments to the Claims:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

Listing of Claims:

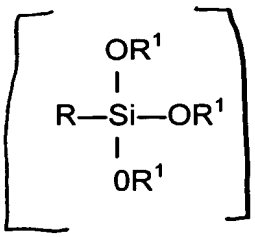
1. (Currently Amended): A semiconductor device in which, at least, part of the semiconductor is coated or sealed with a thermosetting resin material, wherein the thermosetting resin material comprises a solvent-free thermosetting resin composition, which comprises (a) an epoxy resin ~~(a), a~~(b) a reaction product ~~(b) of the reaction~~ of an organosilicon compound, represented by the general formula (1)

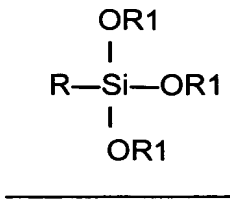


$$R—Si(OR^1)_3 \qquad R—Si(OR1)_3 \qquad (1)$$

(where R is an organic group containing a functional group reactive with an epoxy resin by addition reaction; and R1 is a methyl or ethyl group), with water in the presence of the epoxy resin ~~(a)~~, ~~and~~(c) a curing agent ~~(c)~~, and (d) an inorganic filler, as essential components; and said composition is in a liquid form at ~~a~~ room temperature ~~(25C°), and inorganic filler as essential components~~(25°C).

2. (Currently Amended): A semiconductor device in which a semiconductor chip and a lead frame are bonded together using a die bonding material containing a thermosetting resin material, wherein the thermosetting resin material comprises a solvent-free thermosetting resin composition, which comprises (a) an epoxy resin ~~(a), a product (b) of the reaction~~, (b) a reaction product of an organosilicon compound, represented by the general formula (1)

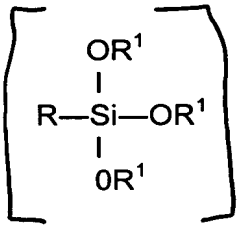


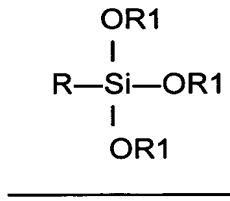


(1)

(where R is an organic group containing a functional group reactive with an epoxy resin by addition reaction; and R1 is a methyl or ethyl group), with water in the presence of the epoxy resin ~~(a), and~~, (c) a curing agent ~~(c)~~, and (d) metallic powder, as essential components; and said composition is in a liquid form at a room temperature (25°C)~~, and metallic powder as essential components~~.

3. (Currently Amended): A semiconductor device in which the semiconductor and a wiring board are mounted using a thermosetting resin material, wherein the thermosetting resin material comprises a solvent-free thermosetting resin composition, which comprises (a) an epoxy resin, ~~(a), a product (b) of the reaction~~(b) a reaction product of an organosilicon compound, represented by the general formula (1)





(1)

(where R is an organic group containing a functional group reactive with an epoxy resin by addition reaction; and R1 is a methyl or ethyl group), with water in the presence of the epoxy resin, ~~(a), and~~(c) a curing agent, ~~(c) as essential components~~ and (d) conductive metallic powder, as essential components; and said composition is in a liquid form at a room temperature (25°C)~~, and conductive metallic powder as essential components~~.